

### IN THE CLAIMS

Please amend claims 1, 6, and 13 as follows:

1. (Twice Amended) Droplet deposition apparatus comprising:

a fluid chamber having actuator means actuatable by electrical signals to effect ejection of droplets from the fluid chamber through a nozzle;

drive circuit means for supplying the electrical signals to the actuator means; and

conduit means for conveying droplet fluid to and from said fluid chamber, said drive circuit means being in substantial thermal contact with said conduit means so as to transfer a substantial part of the heat generated in said drive circuit to said droplet fluid.

6. (Amended) Droplet deposition apparatus comprising:

at least one droplet ejection unit comprising a plurality of fluid chambers, actuator means and a plurality of nozzles arranged in a row, said actuator means being actuatable to eject a droplet of fluid from a fluid chamber through a respective nozzle; and

a support member for said at least one droplet ejection unit, said support member comprising at least one droplet fluid passageway communicating with said plurality of fluid chambers and arranged so as to convey droplet fluid from said fluid chambers in a direction substantially parallel to said nozzle row and to transfer a substantial part of the heat generated during droplet ejection to said conveyed droplet fluid.

13. (Amended) Droplet deposition apparatus comprising:

a fluid chamber, at least part of which is formed from a first material having a first coefficient of thermal expansion, said chamber being associated with actuator means actuatable to eject a droplet from the chamber and having a port for the inlet of droplet fluid thereto;

a support member for said fluid chamber and including a passageway for supply of droplet fluid to said port, the support member being defined at least in part by a second material having a second coefficient of thermal expansion greater than said first coefficient; and

means for attaching the fluid chamber to the support member in order to substantially avoid transfer of thermal deformation of the support member to said fluid chamber.